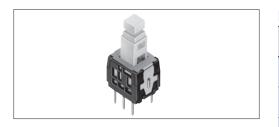


2.2mm-travel Medium-sized Vertical Type



Easy to use mid-size vertical type push switch.



Typical Specifications

- 136.00. 0600000					
Items	Specifications				
Rating (max.) / (min.) (Resistive load)	0.1A 30V DC / 50μA 3V DC				
Contact resistance (Initial performance)	100m Ω max.				
Operating force	2±1N				
Operating life with load	10,000cycles (0.1A 30V DC)				

Detector

Slide

Push

Rotary

Encoders

Power

Dual-in-line

Package Type

TACT Switch™

Product Line

Changeover	Travel	Total travel	Mounting	Poles	Operation	Terminal	Location	Minimum ord	ler unit (pcs.)	Product No.	
timing	(mm)	(mm)	method	roles	S Operation	type	type lug	Japan	Export	Froduct No.	
	2.2	2.2 3 PC	PC board 2	2	Latching	mentary Straight stching	With	100	6,000	SPPH410100	
					Momentary					SPPH410200	
Non shorting					Latching		Without			SPPH420100	
							O i NACI			SPPH430100	
								Momentary	Snap-in	With	

Note Other varieties are also available. Please inquire.

Packing Specifications

_	uik		
	Number of p	Export package	
	1 case / Japan	measurements (mm)	
Γ	1 200	6.000	400 × 270 × 290

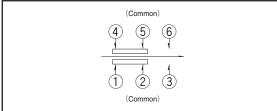
Horizontal Type

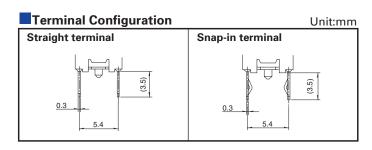
Vertical Type

Dimensions	Unit:mm
Style	PC board mounting hole dimensions (Viewed from the direction A)
A 3.3 (0.2) 8.5	For location lug ### ### ### ### ####################

Note Dimensions drawing is for type with location lugs.

Circuit Diagram (Viewed from Direction A)





Push Switches

■ List of Varieties

Detector

Slide

Push

Rotary

Encoders

Power

Dual-in-line Package Type

TACT Switch $^{\text{TM}}$

Horizontal Type

Vertical Type	

			Vertical								
	Series		SPPH2	SPPH4	SPPH1	SP	EF	SPED2	SPED3	SPED4	SPED5
Photo				1	8			8	Sin .		
w		W	6	6.5	10	9.4		14		13.5	
Dimensi (mm)	ons D		6.5	8.5	10	9		16.8	18 18.2		18.2
		н	6.5	8	.5	6	.9	18.3	16.97	13.1	18
Tra	vel (mm))	1	2.2	1.5	1.	.5	_	_	_	_
Total t	ravel (m	ım)	1.5	3	2.5	2.	.7	4.5		3.8	
Numb	er of po	les		2		-	1	2		1	
	erating ature ra		-	10°C to +60	°C	_	40°C to +85	°C	_	40°C to +95	°C
Auton	notive ι	ıse	_	_	•	•	•	•	•	•	•
Lif	e cycle		* 3	*3	3	*	13	*3 *3 *3			*3
	ng (max stive loa		0.1A 12V DC	0.1A 3	0V DC		1A 14.5V DC			2A 14.5V DC	
	ng (min. stive loa		_	_		50 μ A 3V DC	;	_	_	_	_
Durability	Operat withou		10,000 cycles 50 max.	$10,000$ cycles 100 m Ω max.	10,000 cycles 40 max.	_	_	_	_	_	_
Durability	Operating li (at max. ra		$10,000$ cycles 50 m Ω max.	$10,000$ cycles 100 m Ω max.	10,000 cycles 40 max.	30,000cycles 100 m $Ω$ max.					
		contact tance	$30 \text{m}\Omega$ max.	100m Ω max.	$20 m \Omega$ max.			100mΩ	Ω max.		
Electrical performance		ation tance	100N	/IΩ min. 500	V DC	3M Ω min. 100V DC 3M Ω min. 500V DC					
		age oof	500V AC for 1minute			100V AC for 1minute					
	Tern stre	ninal ngth	5	5N for 1minute		_	_	_	_	_	Wire strength 30N
Mechanical performance	Actuator		30	N	50N	90N		90N	98N	90N	98N
	strength	Pulling direction	_	10N	_	30N		_	_	_	_
	Cold		-20±2°C for 96h			-40±2°C for 96h					
Environmental performance	Dry heat			8	5±2°C for 96	sh			105±2℃	for 192h	
	Damp	heat				40±2℃,	90 to 95%R	H for 96h			
	Page		127	129	130	132	132	134 135 135 135			

Push Switches Soldering ConditionsPush Switches Cautions137138

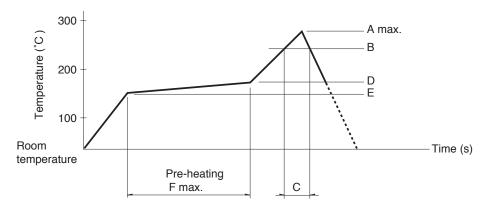
Note • indicates applicability to all products in the series.

Push Switches Soldering Conditions

■ Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



Series (Reflow type)	A (℃) 3s max.	B (℃)	C (s)	D (℃)	E (℃)	F (s)
SPEG	260	230	40	180	150	120
SPEJ						
SPEF						
SPEH						

Horizontal Type Vertical Type

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPPH4, SPPH1	350±5℃	3+1/0s	
SPED2, SPED4	350±5℃	3±1s	
SPEJ	350±5℃	4s max.	
SPEG, SPPH2, SPEF	350±10°C	3s max.	
SPEH	350°C max.	3s max.	
SPUJ, SPUP	300±5℃	3+1/0s	

■Reference for Dip Soldering

(For PC board terminal types)

Series	Ite	ms	Dip soldering		
Series	Preheating temperature Preheating time		Soldering temperature	Duration of immersion	
SPPJ3	100°C max.	60s max.	260±5℃	5±1s	
SPUN	100°C max.	60s max.	260±5℃	10±1s	
SPUJ, SPUP, SPPH2, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	

Slide

Detector

Push

Rotary

Encoders

Power

Dual-in-line Package Type

TACT Switch™